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					Date* Cited in Foreign P.O.		ranslation No
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Π	PDD	Seppala, A, "Flip Chip Joining on GR-4: International Journal of Microcircuits and 24, Number 2, Second Quarter 2001, pp.	d Electronic Packag				
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FORM PT	0-1449	(Modified for Citation of Foreign			DOCKET NO.	SERIA	
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Compl	ete if Known	
Application Number	10/091, 086	
Filing Date	03/05/2002	
First Named Inventor	Stewart, Steven L.	
Art Unit		
Examiner Name		-
Attorney Docket Number	115 01 012	

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Examiner Initials*	Cite No.1		ocument Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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First Named Inventor	Stewart, Steven L.	
Art Unit		
Examiner Name		
Attorney Docket Number	115.01.012	

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